# tehnot≡ka

# Informacije o proizvodu (EN)

HP računar Pro Tower 290 G9 12/256GB (6D470EAR)



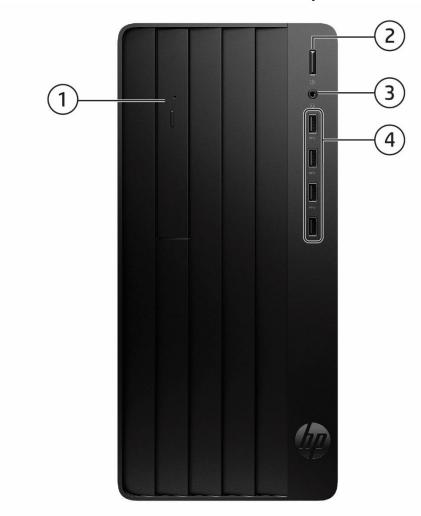
Tehnoteka je online destinacija za upoređivanje cena i karakteristika bele tehnike, potrošačke elektronike i IT uređaja kod trgovinskih lanaca i internet prodavnica u Srbiji. Naša stranica vam omogućava da istražite najnovije informacije, detaljne karakteristike i konkurentne cene proizvoda.

Posetite nas i uživajte u ekskluzivnom iskustvu pametne kupovine klikom na link:

https://tehnoteka.rs/p/hp-racunar-pro-tower-290-g9-12256gb-6d470ear-akcija-cena/

Overview

### HP Pro Tower 290 G9 Desktop PC



- 1. Slim-height Bay supporting an optical disk drive (Optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- (4) SuperSpeed USB 5Gbps signaling rate port<sup>1</sup>

#### Not shown

**Slots**(1) PCI Express 4.0 x16<sup>2</sup>

(1) PCI Express 3.0 x1 (1) M.2 for WLAN

(1) M.2 2242/2280 storage

**Bays** 

(2) 3.5"

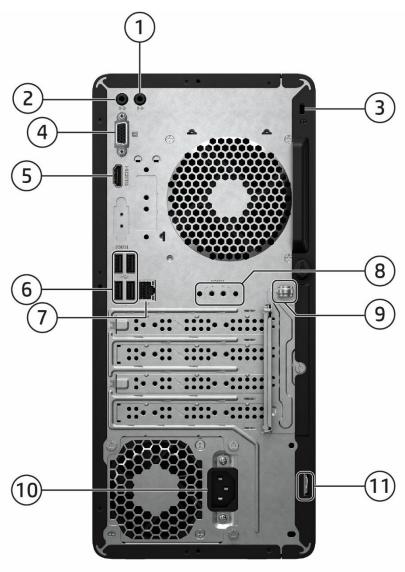
(1) 9.5mm internal optical drive bay

- 1. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1.
- 2. Support discrete graphic cards and storage devices only.



Overview

### HP Pro Tower 290 G9 Desktop PC



- 1. **Audio Line out**
- 2. Audio Line in
- 3. Standard lock slot
- 4. VGA Port1
- 5. HDM Port1
- **Not shown**
- (1) Parallel Port (Optional via PCIex1 slot)
- (1) 4 Serial Port (Optional via PCIex1 slot)3
- (1) Intrusion Sensor (Optional)

- 1. Port will be covered up when configured with processor which is without internal graphics. 2. Power cord connector will be in different position, depends on which power supply configured.
- 3. Available in select countries only.

6.

7.

8.

9.

10.

11.

Connector (4) USB 2.0 port

Power Cord Connector<sup>2</sup>

Integrated accessories cable lock

**RJ-45 Network** Serial port (optional)

Padlock Loop

Overview

#### **AT A GLANCE**

- Windows 11 Pro 64, Win 11 Home 64 or FreeDOS.
- Intel® H670 chipset supporting Intel® 13<sup>th</sup> or 14<sup>th</sup> processors¹ featuring Intel® UHD Graphics.
- Supports an optional discrete graphics card.
- Integrated 10/100/1000 Ethernet Controller or Realtek RTL8821CE-CG 802.11 a/b/g/n/ac (1x1) Wi-Fi5 and Bluetooth® 4.2 Wireless Card or Realtek RTL8822CE-CG 802.11 a/b/g/n/ac (2x2) Wi-Fi5 and Bluetooth® 5.0 Wireless Card or Realtek RTL8852BE 802.11 a/b/g/n/ac/ax (2x2) Wi-Fi6 and Bluetooth® 5.3 Wireless Card
- Up to 64GB DDR4-3200 Unbuffered Memory (UDIMM).
- Independent monitor support via VGA and HDMI interfaces.
- TPM2.0 support (PCI version support dTPM, and the non-PCI version support fTPM)<sup>1</sup>.
- Supports both Hard Disk Drives and PCle® NVMe™ M.2 SSD or PCle® NVMe™ TLC M.2 SSD.
- Up to 8 USB Ports.
- 180W/350W/500W 90% HE power supply and 260W 92% HE power supply.
- Security cable lock supported (sold separately).
- Intrusion sensor supported (Optional).
- Optional HP Services available<sup>2</sup>; terms and conditions vary by country; certain restrictions and exclusions apply.

#### 1. Available on select skus only.

2. HP Services are optional. Service levels and response times for HP Care Services may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <a href="http://www.hp.com/go/cpc">http://www.hp.com/go/cpc</a>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

#### **PRODUCT NAME**

HP Pro Tower 290 G9 Desktop PC

#### **OPERATING SYSTEM**

Preinstalled Windows 11 Pro<sup>1</sup>

Windows 11 Home - HP recommends Windows 11 Pro for Business<sup>1</sup>

Windows 11 Home Single Language - HP recommends Windows 11 Pro for Business1

FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See <a href="http://www.windows.com">http://www.windows.com</a>.



Standard Features and Configurable Modules

#### **PROCESSORS**

	12th Gen PCI	13th Gen PCI	14th Gen PCI	12th Gen Non-PCI	13th /14th Gen Non-PCI
12 <sup>th</sup> Gen Processor	Х	Х	Х	Х	
13 <sup>th</sup> Gen Processor		X	Х		Х
14th Gen Processor			Х		Х

### Intel® Celeron® Processors1,2

Intel® Core™ 300 with Intel UHD Graphics 710 (3.9 GHz P-core base frequency, 6 MB L3 cache, 2 P-cores, 4 threads)

### Intel 13th Processors

#### Intel® Core™ i31

CPU Intel Core i3-13100 4C 3.4GHz 3200MHz 60W (3.4GHz, turbo up to 4.5GHz, 12MB cache, 4 cores)

#### Intel® Core™ i51

CPU Intel Core i5-13400 10C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.6GHz, 20MB cache, 10 cores) CPU Intel Core i5-13500 14C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.8GHz, 24MB cache, 14 cores)

#### Intel® Core™ i71

CPU Intel Core i7-13700 16C 2.1GHz 3200MHz 65W (2.1GHz, Up to 5.2GHz with Intel® Turbo Boost², 30MB cache, 16 cores)

### Intel 14<sup>th</sup> Processors

#### Intel® Core™ i31

Intel® Core™ i3-14100 with Intel UHD Graphics 730 (3.5 GHz P-core base frequency, up to 4.7 GHz P-core Max Turbo frequency, 12 MB L3 cache, 4 P-cores, 8 threads).

#### Intel® Core™ i51

Intel® Core™ i5-14600 with Intel UHD Graphics 770 (2.0 GHz E-core base frequency, 2.7 GHz P-core base frequency, up to 3.9 GHz E-core Max Turbo frequency, up to 5.2 GHz P-core Max Turbo frequency, 24 MB L3 cache, 6 P-cores and 8 E-cores, 20 threads), supports Intel® vPro® Technology.

Intel® Core™ i5-14500 with Intel UHD Graphics 770 (1.9 GHz E-core base frequency, 2.6 GHz P-core base frequency, up to 3.7 GHz E-core Max Turbo frequency, up to 5.0 GHz P-core Max Turbo frequency, 24 MB L3 cache, 6 P-cores and 8 E-cores, 20 threads), supports Intel® vPro® Technology.

Intel® Core™ i5-14400 with Intel UHD Graphics 730 (1.8 GHz E-core base frequency, 2.5 GHz P-core base frequency, up to 3.5 GHz E-core Max Turbo frequency, up to 4.7 GHz P-core Max Turbo frequency, 20 MB L3 cache, 6 P-cores and 4 E-cores, 16 threads).

#### Intel® Core™ i7<sup>1</sup>

Intel® Core™ i7-14700 with Intel UHD Graphics 770 (1.5 GHz E-core base frequency, 2.1 GHz P-core base frequency, up to 4.2 GHz E-core Max Turbo frequency, up to 5.3 GHz P-core Max Turbo frequency, 33 MB L3 cache, 8 P-cores and 12 E-cores, 28 threads), supports Intel® vPro® Technology.

1. Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

2. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See <a href="http://www.intel.com/technology/turboboost">http://www.intel.com/technology/turboboost</a> for more information.



Standard Features and Configurable Modules

### **CHIPSET**

Intel® H670 Chipset

#### **GRAPHICS**

Graphic Card	12th Gen PCI	13th Gen PCI	14th Gen PCI	12th Gen Non-PCI	13th /14th Gen Non-PCI
Intel Arc A380 6GB GDDR6 GFX	Х	Х	Х		X
NVIDIA GeForce RTX 4060 8GB GDDR6 GFX		Х	Х		Х
AMD Radeon RX 6300 2GB GDDR6 GFX	Х	Х	Х	Х	X
NVIDIA GeForce RTX 3050 8GB GDDR6 GFX	Х				
AMD Radeon RX 6400 4GB GDDR6 GFX	Х			Х	
AMD Radeon RX 6600XT 8GB GDDR6 GFX	Х			Х	

### Integrated<sup>1,2</sup>

Intel® UHD

**Graphics 770** 

Graphics 730

Graphics 710

#### **Discrete Graphics**

AMD Radeon™ RX 6300 Graphics (2 GB GDDR6) Intel Arc A380 Graphics (6GB GDDR6) NVIDIA® GeForce RTX 4060 Graphics (8 GB GDDR6)

- 1. HD content required to view HD images.
- 2. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.
- \*NOTE: Available in select countries only.



# of Slots 2 DIMM<sup>1</sup>

## QuickSpecs

Standard Features and Configurable Modules

32GB DDR4-3200 UDIMM NECC (2x16GB)<sup>2</sup> 64GB DDR4-3200 UDIMM NECC (2x32GB)<sup>2</sup>

#### **MEMORY**

Memory	12th Gen PCI	13th Gen PCI	14th Gen PCI	12th Gen Non-PCI	13th /14th Gen Non-PCI
DDR4 3200	X	X		X	Х
DDR5 4800			X		
DDR5 5600			Х		

Form Factor	Type	Maximum		
Tower	DDR4 3200	64 GB capacity		
4GB DDR4-3200 UDIM	M NECC (1x4GB)			
8GB DDR4-3200 UDIM	M NECC (1x8GB)			
8GB DDR4-3200 UDIMM NECC (2x4GB) <sup>2</sup>				
16GB DDR4-3200 UDII	MM NECC (1x16GB)			
16GB DDR4-3200 UDIMM NECC (2x8GB) <sup>2</sup>				
32GB DDR4-3200 UDII	MM NECC (1x32GB)			

<sup>1.</sup> Memory modules support data transfer rates up to 2933 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

<sup>2.</sup> Memory speed 3200 MT/s can be achieved via two UDIMMs per channel (2DPC) when populated with the same part number. **NOTE:** DDR4-2933 UDIMM is only available for 10<sup>th</sup> Gen i7 processor.

Standard Features and Configurable Modules

#### **STORAGE**

**NOTE:** Starting from November 1<sup>st</sup>, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

#### SATA3 - 3.5" or 2.5" 6Gb/s HDDs

2TB 7200 RPM SATA Hard Disk Drive 1TB 7200 RPM SATA Hard Disk Drive

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

#### **Solid State Drives**

256GB\* M.2 NVMe

512GB\* M.2 NVMe

1TB\* M.2 NVMe

128GB\* M.2 2230 PCIe NVMe\*

128GB\* M.2 2280 PCIe NVMe Three Layer Cell SSD

256GB\* M.2 2280 PCIe NVMe Three Layer Cell SSD

512GB\* M.2 2280 PCIe NVMe Three Layer Cell SSD

1TB\* M.2 2280 PCIe NVMe Three Layer Cell SSD

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

\*NOTE: Available in select countries only.

### **OPTICAL DISC DRIVES**

DVD-ROM 9.5mm DVD-Writer<sup>1</sup> 9.5mm

1. HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Standard Features and Configurable Modules

### **NETWORKING<sup>1</sup>**

#### Ethernet (RJ-45)

Integrated 10/100/1000M GbE LAN

#### Wi-Fi® and Bluetooth®

Realtek RTL8852BE 802.11 a/b/g/n/ac/ax (2x2) Wi-Fi6 and Bluetooth® 5.3 Wireless Card Realtek RTL8822CE-CG 802.11 a/b/g/n/ac (2x2) Wi-Fi5 and Bluetooth® 5.0 Wireless Card Realtek RTL8821CE-CG 802.11 a/b/g/n/ac (1x1) Wi-Fi5 and Bluetooth® 4.2 Wireless Card

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

**NOTE:** Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.

#### **AUDIO / MULTIMEDIA**

Realtek ALC3867-CG
Integrated Hi-Definition Audio
Combo Jack, Headphone / Microphone
Line-in / Line-out (3.5mm)

### **KEYBOARDS AND POINTING DEVICES<sup>1</sup>**

#### Keyboard

HP USB 320K Keyboard
HP 125 BLK Wired Keyboard
HP 125 Antimicrobial Wired Keyboard (china only)
HP PS/2 Business Slim Keyboard (for machine configured with PS/2 port)

#### Mouse

HP PS/2 mouse (for machine configured with PS/2 port)
HP Wired Desktop 320M mouse
HP 125 Wired Mouse
HP 128 Laser Wired Mouse
HP 125 Antimicrobial Wired Mouse (china only)

1. Keyboards and mouse are optional or add-on features. A keyboard and mouse are required for this device. If you do not already have a keyboard and mouse, please refer to a list of compatible keyboards on the "Recommended Accessories" page.



Standard Features and Configurable Modules

### **PORTS**

Front I/O	12th Gen PCI	13th Gen PCI	14th Gen PCI	12th Gen Non-PCI	13th /14th Gen Non-PCI
ODD (option)	Х	Х	X	Х	Х
Power Button	Х	Х	Х	Х	Χ
Combo jack, Headphone/ Microphone	Х	Х	Х	Х	Х
SD card reader (option)	Х				
SuperSpeed USB 5Gbps signaling rate port	(4)	(2)	(3)	(4)	(4)
SuperSpeed USB 10Gbps signaling rate port	(2)	(2)	(2)		
USB 2.0 port		(1)			
USB-C 3.2 G1 (5G)		(1)	(1)		

#### Intel 13<sup>th</sup>, 14<sup>th</sup> Gen Front

Slim-height Bay - supporting an optical disk drive (Optional)

**Power Button** 

Combo jack, Headphone / Microphone

(4) SuperSpeed USB 5Gbps signaling rate port\*

#### Not shown

- (1) PCI Express 4.0 x16
- (1) PCI Express 3.0 x1
- (1) Full-height PCI (Available on selected sku)
- (1) M.2 for WLAN
- (1) M.2 2230/2280 storage

#### Rear

**Audio Line out** 

Audio Line in

**HDMI** Port

**VGA Port** 

Standard Lock Slot

(4) USB 2.0 port

**RJ-45 Network connector** 

Power cord connector

Padlock loop

Integrated accessories cable lock

Serial port (optional)



Standard Features and Configurable Modules

#### **Not shown**

- (1) Parallel Port (Optional via PCIex1 slot)
- (1) 4x Serial port (Optional via PClex1 slot)\*
- (1) Intrusion Sensor (Optional)

NOTE\*: Available in select countries only.

NOTE\*\*: SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

#### **BAYS**

- (1) 9.5mm external slimline ODD bay (Optional)
- (1) 3.5" internal HDD or bay
- (1) 3.5" internal HDD bay (share bay with caddy)



Standard Features and Configurable Modules

#### SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

#### **Security and Protection**

McAfee\* LiveSafe™1

#### **Productivity**

Microsoft 365<sup>2</sup>

Xerox® DocuShare® (90 days free trial offer)3

#### **ODD Playback**

sMedio True DVD for HP

#### **Movies**

Netflix4

#### **App Stores and Content Purchasing**

Amazon<sup>4</sup>

#### **HP Utilities and Support**

HP Documentation
HP Audio Switch<sup>5</sup>
HP Support Assistant
myHP

#### **BTB**

**HP Setup Integrated 00BE** 

#### Hardware Enabling Drivers or software utility

**HP System Event Utility** 

- 1. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration
- 2. Sold separately and requires Internet access for activation.
- 3. Simply sign up and start using Xerox® DocuShare® Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 day free trial period. See visit https://http://www.xerox.com/docusharego for details.
- 4. Internet access required and not included.
- 5. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience.
- \*NOTE: Available in Latin America countries only.

#### **POWER SUPPLY<sup>1</sup>**

180 W

EPA90 (Gold) +12V

260W

EPA92 +12V

350 W

EPA90 (Gold) Power Supply

500 W

EPA90 (Gold) Full range 115V/230V

1. All power supplies are not available in every region.



Standard Features and Configurable Modules

#### **DIMENSIONS AND WEIGHT**

#### **Dimensions**

6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm)

#### Weight

10.4 lbs / 4.7 kg

#### UNIT ENVIRONMENT AND OPERATING CONDITIONS

#### **General Unit Operating Guidelines**

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit
  is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the
  enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 5° to 35° C<sup>1</sup>

Non-operating: -30° to 60° C1

Relative Humidity Operating: 5% to 90% (non-condensing at ambient)

Non-operating: 5% to 90% (non-condensing at ambient)

Maximum Altitude (unpressurized) Operating: 5000 m

Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

### Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT® Gold\* or EPEAT Silver\*\* registered in the United States. See <a href="http://www.epeat.net">http://www.epeat.net</a> for registration status in your country.
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Commission Regulation (EC) No 617/2013 (ErP Lot 3)

Note\*: Only available on 13th Gen CPU Legacy SKU, except Japan.

Note\*\*: Available on all 12th Gen CPU SKUs, 13th Gen non-legacy SKUs, and 13th Gen legacy SKUs for Japan.



Standard Features and Configurable Modules

Sustainable Impact Specifications	<ul> <li>Product Carbon Footprint (hp.com)</li> <li>29.8% post-consumer recycled plastic</li> <li>Low halogen</li> <li>Outside Box and corrugated cushions are 100% sustainably sourced and recyclable</li> <li>Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable.</li> <li>Bulk packaging available</li> </ul>			
System Configuration	The configuration used for the Ene Desktop model is based on a "Typic		ed Noise Emissions data for the	
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	16.34 W	17.06 W	16.41 W	
Normal Operation (Long idle)	16.31 W	16.04 W	16.15 W	
Sleep	1.74 W	1.73 W	1.76 W	
Off	0.32 W	0.33 W	0.32 W	
Heat Dissipation*		) ENERGY STAR® specifications f rations, then energy efficiency	for computers. If a model family does not data listed is for a typically configured PC	
	115VAC, BUHZ	230VAC, 50H2	TOUVAC, SUNZ	
Normal Operation (Short idle)	55.72 BTU/hr	58.17 BTU/hr	55.96 BTU/hr	
Normal Operation (Long idle)	55.62 BTU/hr	54.70 BTU/hr	55.07 BTU/hr	
Sleep	5.93 BTU/hr	5.90 BTU/hr	6.00 BTU/hr	
Off	1.09 BTU/hr	1.13 BTU/hr	1.09 BTU/hr	
	<b>NOTE:</b> Heat dissipation is calculated ba hour.	sed on the measured watts, ass	suming the service level is attained for one	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power Sound Pressure (L <sub>WAd</sub> , bels) (L <sub>pAm</sub> , decibels)			
Typically Configured – Idle	3.6 25		25	
Fixed Disk – Random writes	3.7		26	
Optical Drive – Sequential reads	3.8		26	
Longevity and Upgrading	This product can be upgraded, poss features and/or components conta Spare parts are available througho production.	ined in the product may inclu		



Standard Features and Configurable Modules

Batteries	This hattery	(s) in this product comply with EU Directive 2006/66/EC			
Batteries	This bactery	(3) III this product compty with Lo bilective 2000/00/LC			
	Batteries use	ed in the product do not contain:			
		ater the1ppm by weight			
	Cadmium greater than 20ppm by weight				
	Battery size: Battery type	CR2032 (coin cell)			
Additional Information		ct is in compliance with the Restrictions of Hazardous Subs	tances (RoHS) directive -		
	2011/65/EC	•	transco (transco		
	• This HP pro	oduct is designed to comply with the Waste Electrical and E	lectronic Equipment (WEEE)		
	Directive – 2				
		ct is in compliance with California Proposition 65 (State of	California; Safe Drinking Water		
		forcement Act of 1986).	et also Cald lavel and		
	http://www.	ct is in compliance with the IEEE 1680.1 (EPEAT) standard a	at the Gold level, see		
		epeat.net. rts weighing over 25 grams used in the product are marked	1 ner IS011469 and IS01043		
		ct contains 28.2% post-consumer recycled plastic (by wt.)	a per 1501 1405 una 150 1045.		
		ct is 92.9% recycle-able when properly disposed of at end	of life.		
Packaging Materials	External:	PAPER/Paperboard	1220 g		
	Internal:	PAPER/Molded Pulp	580 g		
		PLASTIC/Polyethylene low density - LDPE	40 g		
		packaging material contains at least 0.0% recycled content			
		ted paper packaging materials contains at least 35.0% rec			
	HP Inc. complies fully with materials regulations. We were among the first companies to extend the				
		in the European Union (EU) Restriction of Hazardous Subst			
	•	rldwide through the HP GSE. HP has contributed to the dev n Europe, as well as China, India, and Vietnam.	relopment of related		
		he RoHS directive and similar laws play an important role i			
		of substances of concern. We have supported the inclusion			
		C, BFRs, and certain phthalates—in future RoHS legislationics products.	n that pertains to electrical		
	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS				
		s for virtually all relevant products by July 2013, and we w			
	scope of the	commitment to include further restricted substances as re	egulations continue to evolve.		
		copy of the HP RoHS Compliance Statement, see HP RoHS p			
Material Usage		does not contain any of the following substances in exces	s of regulatory limits (refer to		
		ral Specification for the Environment at hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pd	£).		
	• Asbestos	np.com/npiino/globalcitizensiip/environnent/pai/gse.pa	1).		
	Certain Azo Colorants				
Certain Azo Cotorants     Certain Brominated Flame Retardants — may not be used as flame retardants in plastics.			ardants in plastics		
	• Cadmium	·	•		
		d Hydrocarbons			
	Chlorinated				
	Formaldeh				
		ed Diphenyl Methanes nates and sulfates			
		ead compounds			
		kide Batteries			
	Piercurie Oniue Butteries				



Standard Features and Configurable Modules

	Nickel – finishes must not be used on the external surface designed to be frequently handled or
	carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	• Radioactive Substances
De also sisse Hannes	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
Management and Recycling	recycle your product, please go to: <a href="http://www.hp.com/go/reuse-recycle">http://www.hp.com/go/reuse-recycle</a> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <a href="http://www.hp.com/go/recyclers">http://www.hp.com/go/recyclers</a> . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.  Global Citizenship Report <a href="http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html">http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html</a>
	Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Standard Features and Configurable Modules

#### **SERVICE AND SUPPORT**

On-site Warranty<sup>1</sup>: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day<sup>2</sup> service for parts and labor and complimentary limited technical support<sup>3</sup>. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack<sup>4</sup> To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

- 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
  2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3: Technical support applies only to HP-configured and third-party HP qualified hardware and software.
- 4: Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <a href="http://www.hp.com/go/cpc">http://www.hp.com/go/cpc</a>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications - Graphics

#### **GRAPHICS**

Intel® UHD Graphics (integrate	ed)		
Graphics Controller	Integrated		
DisplayPort™	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 4 displays connected to any output controlled by Intel® Graphics		
НОМІ	Supports HDMI 2.0a features Supports HDCP 2.2 Supports audio over HDMI		
VGA	VGA output		
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.		
Maximum Color Depth	up to 10 bits/color		
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12		
Supported Display Resolutions and Refresh Rates	· ·		

**Note:** The actual amount of maximum graphics memory can be less than the amounts listed above depending upon your computer's configuration.

**Note:** other resolutions may be available but are not recommended as they may not have been tested and qualified by HP Only supported on displays connected to the external DisplayPort™ connector.

#### AMD Radeon™ RX 6300 4GB Graphics Card

**Engine Clock** 1512MHz (Game) 2040MHz (Boost)

Memory Clock2000 MHzMemory Size(width)2GB (64-bit)Memory Type512M x 32 GDDR6

 Max. Resolution (HDMI)
 7680 x 4320x 36bpp@60Hz

 Max. Resolution (DP)
 7680 x 4320 x 24bpp@120Hz

Multi Display Support 2 displays

HDCP Compliance Yes

Rear I/O connectors (bracket) HDMI+DP

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 32W

PCB form-factor with bracket LP PCB with FH/LP bracket



Technical Specifications - Graphics

### NVIDIA® GeForce RTX 4060 8GB Graphics Card

**Engine Clock** 1830Mhz **Memory Clock** 17Gbps Memory Size (width) 8GB (128-bit) **Memory Type** 512M x 32 GDDR6 Max. Resolution (DP) 7680 x 4320@60Hz **Multi Display Support** 7680 x 4320@60Hz **HDCP Compliance** Up to 4 displays

Rear I/O connectors (bracket)

Cooling (active/passive) DPx3+ HDMIx1 Total power consumption (W) Active fansink

PCB form-factor with bracket 115W

### Intel® Acr A380 6GB Graphics Card

**Graphic Clock** 2000Mhz **Memory Clock** 1937.5Mhz 6GB (96-bit) Memory Size (width)

512M x 32 GDDR6 **Memory Type** 

Max. Resolution (DP) DP 1.3/1.4a ready / 5K@120Hz/8K@60Hz HDR 12b

Max. Resolution (HDMI) HDMI 2.0b /4K@60HZ

**HDCP Compliance** Up to 4 displays

Rear I/O connectors (bracket) Yes

Cooling (active/passive) DPx3+ HDMIx1

Active fansink with 4 pin fan control Total power consumption (W)

PCB form-factor with bracket 75W



Technical Specifications – Optical Drives

#### **STORAGE\***

**NOTE:** Starting from November 1<sup>st</sup>, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

#### HP 2TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 2TB

**Rotational Speed** 7,200 rpm **Interface** SATA 6Gb/s NCQ

Buffer Size 64MB

 Logical Blocks
 3,907,029,168

 Seek Time
 Read: <8.5 ms</td>

 Write: <9.5 ms</td>

Write: <9.5 ms

 Height
 1.028 in/26.11 mm

 Width
 4.0 in/101.6 mm

**Operating Temperature** 32° to 140° F (0° to 60° C)

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

#### 1TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 1TB

**Rotational Speed** 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 32MB

Logical Blocks 1,953,525,168

Seek Time Single Track: 2.0 ms
Average: 11 ms

Full-Stroke: 21 ms

Height 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

**Operating Temperature** 41° to 131° F (5° to 55° C)

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Technical Specifications – Optical Drives

#### 128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10g
Capacity 128GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen4x

InterfacePCIE Gen4x4Maximum Sequential ReadUp to 2800MB/sMaximum Sequential WriteUp to 600MB/sLogical Blocks250,069,680

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

#### 256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight< 10g</th>Capacity256GBHeight2.38mmLength80mmWidth22mm

InterfacePCIE Gen4x4Maximum Sequential ReadUp to 2700MB/sMaximum Sequential WriteUp to 1000MB/sLogical Blocks500,118,192

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

### 512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

**Drive Weight** < 10a 512GB Capacity Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen4x4 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s



Technical Specifications – Optical Drives

**Logical Blocks** 1,000,215,216

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

### 256GB M.2 2280 PCIe NVMe SSD

**Drive Weight** < 10a Capacity 256GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen4x4 **Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 780MB/s **Logical Blocks** 500,118,192

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

#### 512GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</th>Capacity512GBHeight2.38mmLength80mmWidth22mm

InterfacePCIE Gen4x4Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 860MB/sLogical Blocks1,000,215,216

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Technical Specifications – Optical Drives

#### 128GB M.2 2230 PCIe NVMe SSD

**Drive Weight** < 10g 128GB Capacity Height 2.3mm Length 30mm Width 22mm Interface **PCIE NVMe Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 780MB/s **Logical Blocks** 290,069,680

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** Pyrite

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Technical Specifications — Optical Drives

#### **OPTICAL DISC DRIVES**

#### HP 9.5mm Desktop G2 Slim DVD Writer Drive

**Height** 9.5 mm height

**Orientation** Either horizontal or vertical

Interface type SATA/ATAPI

**Disc recording capacity** Up to 8.5 GB DL or 4.7 GB standard

**Dimensions (W x H x D)** 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

**Weight (max)** 0.31 lb (140 g)

**Read Speeds** DVD-R DL Up to 6X

DVD+R Up to 8X DVD+RW Up to 8X DVD+R DL Up to 6X DVD-R Up to 8X **DVD-RW** Up to 6X CD-R Up to 24X Up to 10X CD-RW DVD-RW, DVD+RW Up to 8X DVD-R DL, DVD+R DL Up to 8X DVD+R, DVD-R Up to 8X DVD-ROM DL, DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X

**Access time** 

(typical reads, including

settling)

Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)

Power

Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

**Environmental conditions** Temperature 41° to 122° F (5° to 50° C)

(operating - non-condensing) Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)



Technical Specifications — Optical Drives

#### HP 9.5mm Desktop G2 Slim DVD-ROM Drive

9.5 mm height Height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 q)

**Read Speeds** DVD-R DL Up to 6X

DVD+R Up to 8X Up to 8X DVD+RW DVD+R DL Up to 6X DVD-R Up to 8X DVD-RW Up to 6X CD-R Up to 24X Up to 10X CD-RW DVD-RW, DVD+RW Up to 8X Up to 8X DVD-R DL, DVD+R DL DVD+R. DVD-R Up to 8X DVD-ROM DL. DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X

**Access time** 

(typical reads, including

settling)

Stop Time 6 seconds (typical)

**Power** Source Slimline SATA DC power receptacle

> DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

**Environmental conditions** (operating - non-condensing) Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)



Technical Specifications – Networking

### **NETWORKING**

10/100/1000 NIC	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCIe + SMBus
	NIC Device Driver Name	PCIe GBE Ethernet Family Controller

Realtek RTL8821CE-CG 80	2.11 a/b/g/n/ac (1x	1) Wi-Fi5 and Bluetooth® 4.2 Wireless Card	
Wireless LAN Standards <sup>1</sup>	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac  1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.		
Interoperability	Wi-Fi® certified modules		
Frequency Bands	802.11b/g/n	2.402 – 2.482 GHz	
		<b>NOTE:</b> The FCC has declared products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 & 15.249 or otherwise disable those channels.	
	802.11a/n	4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz	



Data Rates	802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)		
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security <sup>2</sup>	IEEE and 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI		
	2 Check latest software/driver release for updates on supported security features.		
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power <sup>3</sup>	802.11b: +14dBm minimum 802.11g: +12dBm minimum 802.11a: +12dBm minimum 802.11n HT20(2.4GHz): +12dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum 802.11n HT40(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum		
Power Consumption	•Transmit mode2.0 W •Receive mode1.6 W •Idle mode (PSP)180 mW(WLAN Associated) •Idle mode50 mW(WLAN unassociated) •Connected Standby 10mW •Radio disabled8 mW		
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode		



Receiver Sensitivity <sup>4</sup>	802.11b, 1Mbps: -93.5dBm maximum		
	802.11b, 11Mbps: -84dBm maximum		
	802.11a/g, 6Mbps: -86dBm maximum		
	802.11a/g, 54Mbps: -72dBm maximum		
	802.11n, MCS07: -67dBm maximum		
	802.11n, MCS15: -64dBm maximum		
	802.11ac, MCS0: -84dBm maximum		
	802.11ac, MCS9: -59dBm maximum		
	4 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth <sup>a</sup> communications		
Form Factors	PCI-Express M.2 MiniCard		
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
HP Integrated Module with Blue	tooth® 4.0/4.1/4.2 Wireless Card Techno	logy	
Bluetooth <sup>a</sup> Specification	4.0/4.1/4.2 Wireless Card Compliant	4.0/4.1/4.2 Wireless Card Compliant	
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE: 1 Mbps data rate; throughput up to Legacy: Synchronous Connection Oriente		
Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-EV5)		inks 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or	



Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of + 4 dBm for BR and EDR.		
Receiver Sensitivity Legacy			
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Range	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Electrical Interface	USB 2.0 compliant		
Bluetooth° Software Supported Link Topology	Microsoft Windows Bluetooth® Software		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Certifications Bluetooth <sup>a</sup> Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support		
Certifications Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		



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Wireless LAN Standards	IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g   IEEE 802.11n		
	IEEE 802.1111		
	IEEE 802.11d		
	IEEE 802.11e		
	IEEE 802.11h		
	IEEE 802.11i		
	IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
Interoperability	Wi-Fi® certified		
Frequency Band	802.11b/g/n		
	• 2.402 – 2.482 GHz		
	802.11a/n/ac		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)		
Modulation	Direct Sequence Spread Spectrum		
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security <sup>1</sup>	• IEEE and Wi-Fi® compliant 64 / 128 bit WEP encryption for a/b/g mode only		
	AES-CCMP: 128 bit in hardware		
	802.1x authentication		
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.		
	WPA2 certification		
	• IEEE 802.11i		
	• WAPI		
	1 Check latest software/driver release for updates on supported security features.		
Network Architecture Models	Ad-hoc (Peer to Peer)		
	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		



• 802.11b: +18.5dBm minimum		
• 802.11g: +17.5dBm minimum		
• 802.11a: +18.5dBm minimum		
• 802.11n HT20(2.4GHz): +15.5dBm minimum		
• 802.11n HT40(2.4GHz): +14.5dBm minimum		
• 802.11n HT40(2.4GHz): +14.5dBiff fillifillifillifillifillifillifilli		
• 802.11n HT40(5GHz): +14.5dBm minimum		
• 802.11ac VHT80(5GHz): +11.5dBm minimum		
• 802.11ac VHT160(5GHz): +11.5dBm minimum		
Maximum output power may vary by country according to local regulations.		
• Transmit mode:2.0 W		
• Receive mode:1.6 W		
• Idle mode (PSP) 180 mW (WLAN Associated)		
• Idle mode:50 mW (WLAN unassociated)		
Connected Standby/Modern Standby: 10mW		
Radio disabled: 8 mW		
ACPI and PCI Express compliant power management		
802.11 compliant power saving mode		
802.11b, 1Mbps: -93.5dBm maximum		
802.11b, 11Mbps: -84dBm maximum		
802.11a/g, 6Mbps: -86dBm maximum		
802.11a/g, 54Mbps: -72dBm maximum		
802.11n, MCS07: -67dBm maximum		
802.11n, MCS15: -64dBm maximum		
802.11ac, MCS0: -84dBm maximum		
802.11ac, MCS9: -59dBm maximum		
3 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).		
High efficiency antenna with spatial diversity, mounted in the display enclosure		
Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
PCI-Express M.2 MiniCard with CNVi Interface		
1. Type 2230: 2.3 x 22.0 x 30.0 mm		
2. Type 1216: 1.67 x 12.0 x 16.0 mm		
2. Type 1216: 1.67 x 12.0 x 16.0 mm  1. Type 2230: 2.8g		
2. Type 1216: 1.67 x 12.0 x 16.0 mm  1. Type 2230: 2.8g 2. Type 126: 1.3g		
2. Type 1216: 1.67 x 12.0 x 16.0 mm  1. Type 2230: 2.8g 2. Type 126: 1.3g  3.3v +/- 9%  Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)		
2. Type 1216: 1.67 x 12.0 x 16.0 mm  1. Type 2230: 2.8g 2. Type 126: 1.3g  3.3v +/- 9%  Operating: 14° to 158° F (-10° to 70° C)		
2. Type 1216: 1.67 x 12.0 x 16.0 mm  1. Type 2230: 2.8g 2. Type 126: 1.3g  3.3v +/- 9%  Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)  Operating: 10% to 90% (non-condensing)		
2. Type 1216: 1.67 x 12.0 x 16.0 mm  1. Type 2230: 2.8g 2. Type 126: 1.3g  3.3v +/- 9%  Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)  Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)		



Bluetooth Specification	4.0/4.1/4.2/5.0 Wireless Card Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.	
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW	
Bluetooth Software Supported	Microsoft Windows Bluetooth Software	
Link Topology		
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950-1/IEC62368-1 UL, CSA, and CE Mark	
Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	



	a/b/g/n/ax (2x2) Wi-Fi 6 and Bluetooth® 5.3 Wireless Card		
Wireless LAN Standards	IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac		
	IEEE 802.11d		
	IEEE 802.11e		
	IEEE 802.11h		
	IEEE 802.11i   IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
	IEEE 802.11V		
Interoperability	Wi-Fi certified		
Frequency Band	802.11b/g/n		
	• 2.402 – 2.482 GHz		
	802.11a/n/ac		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)		
Modulation	Direct Sequence Spread Spectrum		
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security <sup>1</sup>	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only		
	AES-CCMP: 128 bit in hardware		
	802.1x authentication		
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.		
	WPA2 certification		
	• IEEE 802.11i		
	• WAPI		
	1 Check latest software/driver release for updates on supported security features.		
Network Architecture Models	Ad-hoc (Peer to Peer)		
	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		



Output Power <sup>2</sup>	<ul> <li>802.11b: +18.5dBm minimum</li> <li>802.11g: +17.5dBm minimum</li> <li>802.11a: +18.5dBm minimum</li> <li>802.11n HT20(2.4GHz): +15.5dBm minimum</li> <li>802.11n HT40(2.4GHz): +14.5dBm minimum</li> <li>802.11n HT20(5GHz): +15.5dBm minimum</li> <li>802.11n HT40(5GHz): +14.5dBm minimum</li> <li>802.11ac VHT80(5GHz): +11.5dBm minimum</li> <li>802.11ac VHT160(5GHz): +11.5dBm minimum</li> <li>2. Maximum output power may vary by country according to local regulations.</li> </ul>	
Power Consumption		
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity <sup>3</sup>	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS07: -67dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 3 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure  Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	<b>Operating:</b> 14° to 158° F (–10° to 70° C) <b>Non-operating:</b> –40° to 176° F (–40° to 80° C)	
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)	
Altitude	<b>Operating:</b> 0 to 10,000 ft (3,048 m) <b>Non-operating:</b> 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON	



Bluetooth Specification	4.0/4.1/4.2/5.0 Wireless Card Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.	
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW	
Bluetooth Software Supported	Microsoft Windows Bluetooth Software	
Link Topology		
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950-1/IEC62368-1 UL, CSA, and CE Mark	
Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	



Technical Specifications - Audio

#### **HIGH-DEFINITION AUDIO**

Type Integrated

HD Stereo Codec Realtek ALC3867-CG

Audio I/O Ports Front side Combo jack for supporting CTIA, Rear side Line-in/ Line-out/ Mic-in jacks

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally.

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

HD Audio Codec Realtek ALC3601

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1K/

48 K/96K / 192K Hz for DAC and 44.1K/ 48K/ 96K/ 192K Hz Hz for ADC

Wavetable Syntheses Yes
Analog Audio Yes
# of Channels on Line-Out Stereo
Internal Speaker Yes

**External Speaker Jack\*** 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally.

NOTE\*: Optional



Technical Specifications - Power

#### **POWER SUPPLY**

**Operating Voltage Range** 90 - 264 VAC Rated Voltage Range 100-240V AC **Rated Line Frequency** 50/60 HZ **Operating Line Frequency** 47 - 63 Hz **Rated Input Current** 180 W: < 2.3A 260 W: ≦3.1A

350 W: <4A 500 W: <6A 180 W active PFC

**Rated Input Current with Energy Efficient\* Power** 

Supply

87/90/87% efficient at 20/50/100% load (115 V) 88/92/88% efficient at 20/50/100% load (230 V);

350 W active PFC

87/90/87% efficient at 20/50/100% load (115 V) 88/92/88% efficient at 20/50/100% load (230 V)

500W active PFC

87/90/87% efficient at 20/50/100% load (115 V) 88/92/88% efficient at 20/50/100% load (230 V)

**DC Output** +12 V

**Current Leakage (NFPA 99:** 2102)

Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or

that contact patients in normal use. Per section 10.3.5.1.

Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care

facility or that contact patients in normal use. Per section 10.3.5.1.

**Power Supply Fan** 180 W/350 W: 70\*25mm (linear type)

500 W: 70x25mm (PWM type)



Technical Specifications – Weights and Dimensions

#### **WEIGHT AND DIMENSIONS**

**Chassis (W x D x H)** 6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm) (w/ bezel)

System Volume 15.1 L

**System Weight\*** 10.4 lb / 4.7 kg

 Packaged
 11.3 x 15.75 x 19.65 in

 (H x W x D)
 287 x 400 x 499 mm

Shipping Weight 17.64lb / 8 kg

Palletization 6 units per layer

Profile 7layer max
42 per pallet

Footprint

-85.31x39.37x47.24 in (2167 x 1000 x1200 mm)



After-Market Options (availability may vary by region)

### **AFTERMARKET OPTIONS**

Туре	Description	Part #
Memory	HP 4GB DDR4-3200 DIMM	13L78AA
	HP 8GB DDR4-3200 DIMM	13L76AA
	HP 16GB DDR4-3200 DIMM	13L74AA
	HP 32GB DDR4-3200 DIMM	13L72AA
Storage	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51AA
	HP PCIe NVME TLC 512GB SSD M.2 Drive	X8U75AA
	HP PCIe Gen 4 NVME TLC M.2 512GB SSD	406L8AA
	HP PCIe Gen 4 NVME TLC M.2 1TB SSD	406L7AA
	HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive	QK555AA
Graphics	NVIDIA T400 4GB GDDR6 3mDP	5Z7E0AA
Security	HP Business PC Security Lock V3 Kit	3XJ17AA
	HP Keyed Cable Lock 10mm kit	T1A62AA
Cables/Adapters	HP HDMI Standard Cable Kit	
	HP USB to Serial Port Adapter	J7B60AA
	HP PCIe x1 Parallel Port Card	N1M40AA
Networking	Intel Ethernet I225-T1 GbE NIC Card	406L9AA
Input	HP Wired Desktop 320K Keyboard	9SR37AA
-	HP Wired Desktop 320M Mouse	9VA80AA
	HP 125 Wired Keyboard	266C9AA
	HP 125 Wired Mouse	265A9AA
	HP 128 Laser Wired Mouse	265D9AA
	HP Wired Desktop 320MK Mouse and Keyboard Combo	9SR36AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 225 Antimicrobial Wired Mouse and Keyboard Combo	286K3AA
Others	HP S101 Speaker bar	5UU40AA



### Change Log

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Date of change:	Version History:	Change	Description of change:
September 13, 2024	From v1 to v2	Correction	Sustainable impact specifications recycled plastic % corrected
	From V2 to V3		
	From V3 to V4		
	From V4 to V5		
	From V5 to V6		
	From V6 to V7		
	From V7 to V8		
	From V8 to V9		
	From V9 to V10		
	From v10 to v11		
	From v11 to v12		
	From v12 to v13		
	From v13 to v14		





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